IBIS Open Forum Minutes

Meeting Date: **April 3, 2009**

VOTING MEMBERS AND 2009 PARTICIPANTS

Actel	(Prabhu Mohan)
Agilent Technologies	Yutao Hu, Fangyi Rao
AMD	Nam Nguyen*
Ansoft Corporation	Steve Pytel
Apple Computer	(Matt Herndon)
Applied Simulation Technology	(Fred Balistreri)
ARM	V. Muniswara Reddy
Cadence Design Systems	Terry Jernberg*, Ambrish Varma
Cisco Systems	Luis Boluna, Tram Bui, Bill Chen, Syed Huq*, Mike LaBonte*, Pedo Miran Huyen Pham, AbdulRahman (Abbey) Rafiq, Ashwin Vasudevan, Zhiping Yang
Ericsson	Anders Ekholm*
Freescale	Jon Burnett, Om Mandhama
Green Streak Programs	Lynne Green
Hitachi ULSI Systems	(Kazuyoshi Shoji)
Huawei Technologies	Xiaoqing Dong, Chunxing Huang, Guan Tao
IBM	Adge Hawes
Infineon Technologies AG	(Christian Sporrer)
Intel Corporation	Michael Mirmak, Jon Powell, Sirisha Prayaga
LSI	Brian Burdick*
Marvell Semiconductor	(Itzik Peleg)
Mentor Graphics	Weston Beal, Vladimir Dmitriev-Zdorov, Zhen Mu, Arpad Muranyi
Micron Technology	Randy Wolff*
Nokia Siemens Networks GmbH	Eckhard Lenski*
Samtec	(Corey Kimble)
Signal Integrity Software	Barry Katz, Walter Katz, Todd Westerhoff*
Sigrity	Sam Chitwood
Synopsys	Ted Mido
Teraspeed Consulting Group	Bob Ross*
Texas Instruments	Pavani Jella
Toshiba (I.S. Corporation)	(Yasumasa Kondo)
Xilinx	David Banas*
ZTE	(Ying Xiong)
Zuken	(Michael Schaeder)

OTHER PARTICIPANTS IN 2009

AET	Mikio Kiyono
Bayside Design	Stephen Coe, Elliot Nahas

Circuit Spectrum	Zaven Tashjian
CST	Antonio Ciccomancini, Martin Schauem
Curtiss-Wright Embedded Computing	J. Phillips
EM Integrity	Guy de Burgh
Exar	Helen Nguyen
GEIA	(Chris Denham)
ICT Solutions	Steven Wong*
IO Methodology	Li (Kathy) Chen, Lance Wang*, Zhi (Benny) Yan
Juniper	Kevin Ko
Leventhal Design & Communications	Roy Leventhal
Maxim Integrated Products	Ron Olisar
Mindspeed Technologies	Bobby Alkay
NetLogic Microsystems	Eric Hsu
Sanmina SCI	Vladimir Drivanenko
Sedona International	Joe Socha
Signal Consulting Group	Timothy Coyle, Nicole Mitchell
Simberian	Yuriy Shlepnev
Xsigo Systems	Robert Badel
Independent	Ian Dodd

In the list above, attendees at the meeting are indicated by *. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

UPCOMING MEETINGS

The bridge numbers for future IBIS teleconferences are as follows:

Date	Telephone Number	Meeting ID
April 23, 2009	-- IBIS Summit at DATE; no teleconference --	
April 24, 2009	1-866-432-9903	121564807

All meetings are 8:00 AM to 9:55 AM US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed within seven days of the corresponding meeting. When calling into the meeting, press 1 to attend the meeting, then follow the prompts to enter the meeting ID. For new, local international dial-in numbers, please reference the bridge numbers provided by Cisco Systems at the following link:

http://www.cisco.com/web/about/doing_business/conferencing/index.html

NOTE: "AR" = Action Required.

INTRODUCTIONS AND MEETING QUORUM

No new participants. Syed Huq noted that he would be running the meeting instead of Michael Mirmak.

CALL FOR PATENTS

Syed Huq called for any patents or pending patents related to the IBIS Version 3.2, 4.0, 4.1, 4.2, or ICM 1.1 specifications. No patents were declared.

MEMBERSHIP UPDATE AND TREASURER'S REPORT

Syed Huq reminded members to please take care of 2009 membership invoices. If you have not received an invoice, please let the board know. Bob Ross reported that nine members have officially renewed so far, so we need to start following up with renewal notices.

REVIEW OF MINUTES AND ARS

Syed Huq called for comments regarding the minutes of the March 13, 2009 IBIS Open Forum teleconference. The minutes were approved without changes.

WEB PAGE UPDATES

No update.

MAILING LIST ADMINISTRATION

Bob Ross reported that everything is working normally.

MODEL LIBRARY UPDATE

Lance Wang reported that he sent an update to the library page to TechAmerica. It should be updated shortly.

PRESS UPDATE

None.

MISCELLANY/ANNOUNCEMENTS

None.

OPENS FOR NEW ISSUES

Bob Ross would like to show the prototype IBIS logos for discussion at the end of the meeting.

INTERNATIONAL/EXTERNAL PROGRESS

- DASC
No update. The DASC file and e-mail archive may be found at:

http://www.dasc.org/

- P1735 Encryption
Syed Huq reported that the group is seeking input from EDA vendors that would like to take part in interoperability testing. The IEEE DASC Study Group on Encryption web reflector archives are found at:

http://www.eda-stds.org/ip-encrypt/hm/

- TechAmerica Status
Bob Ross reported that a new website is up, but it is not completely switched over from the old websites. The new website is:

http://www.techamerica.org/

Three upcoming conferences include Signal Integrity and Power Integrity topics. Information on these is below.

The 13th IEEE Workshop on Signals Propagation on Interconnects (SPI) is May 12-15, 2009 in Strasbourg, France. The keynote speech is on the importance of Signal Integrity, including mention of IBIS…

http://spi.univ-brest.fr

The Electrical Performance of Electronic Packaging and Systems (EPEPS 2009) is October 19-21, 2009 at the Embassy Suites in Portland, OR. This is a major meeting for SI people from universities and industry.

http://www.epep.org/

The 7th International Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC COMPO 2009) is November 17-20, 2009 in Toulouse, France. The call for papers deadline is May 30, 2009.

http://www.emccompo.org

IEC APPROVAL ACTIVITIES

No update.

SUMMIT STATUS

-DATE Planning
Ralf Bruening of Zuken has been organizing the event. It is scheduled for Thursday morning,

April 23, 2009 in Nice, France. Agilent, Sigrity and Zuken are the current sponsors. Several paper presentations are already planned. The fourth announcement went out yesterday. Five papers are planned so far.

-DAC Planning

DAC is scheduled for July 26-31, 2009 in San Francisco. The IBIS summit is scheduled for Tuesday, July 28. Sponsorship is welcome. Elections are also held at this meeting. Let the board know if you are interested in an officer position. The first call for papers should go out in mid-May. Mentor Graphics is a co-sponsor of this event and will help with room arrangements.

-Asia Summits Planning

Meetings in China and Japan are tentatively scheduled in the November-December timeframe. Sponsors are welcome. Bob inquired about interest in the meeting. There is definite interest in China. The meeting will depend upon raising more funds. The meeting will likely be held either in Shenzhen or Shanghai. There is also interest in holding a meeting in Japan. We need to gauge availability of non-Asian participants as well.

Sponsorship opportunities for all upcoming IBIS summits are available, with sponsors receiving free mentions in the minutes, agenda, and other announcements. Contact the IBIS Board for further details.

IBIS QUALITY TASK GROUP

Mike LaBonte reported that the group has about one more month of meetings to wrap up the 1.1 specification. They are cleaning up the correlation section currently. This section will refer to other documents. The group plans to discuss the I/O Buffer Accuracy Handbook next.

The Quality Task Group checklist and other documentation can be found at:

http://www.eda-stds.org/ibis/quality_wip/

IBIS MODEL REVIEW TASK GROUP

No update.

ADVANCED TECHNOLOGY MODELING TASK GROUP

Bob Ross reported that the group discussed IBIS Interconnect Spice the last two meetings. Synopsys supplied their HSPICE manual in Word format to begin cutting down and editing for use in defining IBIS Interconnect Spice. There is also work in progress on an S-parameter block BIRD.

Task group material can be found at:

http://www.eda-stds.org/ibis/macromodel_wip/

AD HOC TASK GROUPS (INTERCONNECT)

Bob Ross reported that the group is not meeting currently.

Task group material can be found at:

http://www.eda.org/ibis/adhoc/interconnect/

NEW ISSUES

Bob Ross showed proposals for new logo designs. The new designs only mention IBIS and remove references to any parent organizations. Bob asked for feedback on six design proposals. Some people liked options B, C and D. Mike LaBonte noted that the outline of the bird in F might print better. Also, there shouldn't be too much color gradient in the IBIS letters. A was eliminated. There will be more discussion in the next meeting.

BIRD111.2: EXTENDED USAGE OF EXTERNAL SERIES COMPONENTS IN EBDS

Bob Ross reported that he has been in contact with Michael Schaeder and Walter Katz who reviewed the changes. He showed the change in text in the BIRD111.3 draft version to clarify the usage of series elements including [R Series], [L Series], [C Series], [Rl Series], [Lc Series], [Rc Series], [Series Current] and [Series MOSFET]. The BIRD111.3 text should be uploaded and sent out next week. He would like it to be considered for a vote at the next meeting.

TOUCHSTONE 2.0 REVIEW

Syed Huq made the third call for comments on the Touchstone 2.0 document. Bob Ross noted that there have been a few minor changes from the last meeting. They are not in the current review document. There has been discussion about normalization verbiage and the multiplier character. Syed asked if we expect it to be up for a vote at the next meeting. Bob noted that we will need to upload the updated document. We should it schedule for a vote.

The draft Touchstone 2.0 document is found at:

http://www.eda.org/ibis/docs/touchstone/touchstone2_forum_review_draft_a.pdf

IBISCHK5 PARSER STATUS

Syed Huq explained that we need to raise funds for the parser development. The first step is to set a price for the parser license. The committee is proposing a price of $2500. We have two commitments of parser purchases currently. The proposed price will also help to cover future IBISCHK5.x development.

A motion was made for vote to set the price at $2500. The vote passed unanimously with the following vote tally:

AMD	yes
Cisco	yes

Ericsson	yes
Intel	yes (by email)
LSI	yes
Micron	yes
Nokia	yes
SiSoft	yes
Teraspeed	yes
Xilinx	yes

IBISCHK4 BUG STATUS

Bob Ross reported that two BUGs are open right now. There are no plans to fix these in the near term, as they are not included in the IBISCHK5 parser development.

The BUG report list is available at the link below:

http://www.eda.org/ibis/bugs/ibischk/

ICMCHK1 BUG STATUS

ICMCHK1 version 1.1.3 has been released, and the executables can be downloaded. All BUGs have been closed at this point.

NEW ISSUES

None.

NEXT MEETING

The next IBIS summit will take place at DATE on April 23, 2009. No teleconference has been arranged for the meeting. The next IBIS Open Forum teleconference will be held April 24, 2009 from 8:00 AM to 10:00 AM US Pacific Standard Time.

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NOTES

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This meeting was conducted in accordance with the GEIA Legal Guides and GEIA Manual of Organization and Procedure.

The following e-mail addresses are used:

majordomo@eda.org
In the body, for the IBIS Open Forum Reflector:
subscribe ibis <your e-mail address>

In the body, for the IBIS Users' Group Reflector:
subscribe ibis-users <your e-mail address>

Help and other commands:
help

ibis-request@eda.org
To join, change, or drop from either or both:

IBIS Open Forum Reflector (ibis@eda.org)
IBIS Users' Group Reflector (ibis-users@eda.org)
State your request.

ibis-info@eda.org

To obtain general information about IBIS, to ask specific questions for individual response, and to inquire about joining the EIA-IBIS Open Forum as a full Member.

ibis@eda.org

To send a message to the general IBIS Open Forum Reflector. This is used mostly for IBIS Standardization business and future IBIS technical enhancements. Job posting information is not permitted.

ibis-users@eda.org

To send a message to the IBIS Users' Group Reflector. This is used mostly for IBIS clarification, current modeling issues, and general user concerns. Job posting information is not permitted.

ibis-bug@eda.org

To report ibischk parser BUGs. The BUG Report Form resides along with reported BUGs at:

http://www.eda.org/ibis/bugs/ibischk/
http://www.eda.org/ibis/bugs/ibischk/bugform.txt

icm-bug@eda.org

To report icmchk1 parser BUGs. The BUG Report Form resides along with reported BUGs at:

http://www.eda.org/ibis/icm_bugs/
http://www.eda.org/ibis/icm_bugs/icm_bugform.txt

To report s2ibis, s2ibis2 and s2iplt bugs, use the Bug Report Forms which reside at:

http://www.eda.org/ibis/bugs/s2ibis/bugs2i.txt
http://www.eda.org/ibis/bugs/s2ibis2/bugs2i2.txt
http://www.eda.org/ibis/bugs/s2iplt/bugsplt.txt

Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

http://www.eigroup.org/ibis/ibis.htm

Check the IBIS file directory on eda.org for more information on previous discussions and results:

http://www.eda.org/ibis/directory.html

IBIS CURRENT MEMBER VOTING STATUS

I/O Buffer Information Specification Committee (IBIS)

Organization	Interest Category	Standards Ballot Voting Status	February 5, 2009	February 20, 2009	March 13, 2009	April 3, 2009
Actel	Producer	Inactive				
Advanced Micro Devices	Producer	Inactive		√		√
Agilent Technologies	User	Inactive	√			
Ansoft	User	Inactive		√		
Apple Computer	User	Inactive				
Applied Simulation Technology	User	Inactive				
ARM	Producer	Inactive	√	√		
Cadence Design Systems	User	Inactive	√			√
Cisco Systems	User	Active	√	√	√	√
Ericsson	Producer	Active	√	√		√
Freescale	Producer	Inactive	√			
Green Streak Programs	General Interest	Inactive		√		
Hitachi ULSI Systems	Producer	Inactive				
Huawei	User	Inactive	√		√	
IBM	Producer	Active		√	√	
Infineon Technologies AG	Producer	Inactive				
Intel Corp.	Producer	Active	√	√	√	
LSI	Producer	Active		√	√	√
Marvell Semiconductor	Producer	Inactive				
Mentor Graphics	User	Active	√	√	√	
Micron Technology	Producer	Active		√	√	√
Nokia Siemens Networks	Producer	Active		√		√
Samtec	Producer	Inactive				
Signal Integrity Software	User	Active	√	√	√	√
Sigrity	User	Inactive	√			
Synopsys	User	Inactive	√			
Teraspeed Consulting	General Interest	Active	√	√	√	√
Texas Instruments	Producer	Inactive		√		
Toshiba	Producer	Inactive				
Xilinx	Producer	Inactive	√			√
ZTE	User	Inactive				
Zuken	User	Inactive				

Criteria for Member in good standing:

- Must attend two consecutive meetings to establish voting membership
- Membership dues current
- Must not miss two consecutive Meetings

Interest categories associated with GEIA ballot voting are:

- Users - Members that utilize electronic equipment to provide services to an end user.
- Producers - Members that supply electronic equipment.
- General Interest - Members are neither producers nor users. This category includes, but is not limited to, Government, regulatory agencies (state and federal), researchers, other organizations and associations, and/or consumers.